

Listing of Claims:

Claim 1 (currently amended) A tin-silver based lead-free solder,
~~characterized by:~~ containing zinc (Zn) added to a solder comprising a tin-silver system
containing no lead.

Claim 2 (currently amended) The tin-silver based lead-free solder ~~according to~~ of claim 1,
~~characterized by~~ further containing indium (In) added thereto.

Claim 3 (currently amended) The tin-silver based lead-free solder ~~according to~~ of claim 1,
~~characterized in that~~ containing 0.3 to 1.0% by weight
~~an amount of zinc (Zn) added is 0.3 to 1.0 wt.%, a~~ the remainder being is tin and silver.

Claim 4 (currently amended) The tin-silver based lead-free solder ~~according to~~ of claim 2,
~~characterized in that~~ containing less than 10% by weight
~~an amount of indium (In) added is less than 10 wt.%, and an amount of 0.1 to 1.0% by~~
weight zinc (Zn) added is 0.1 to 1.0 wt.%, a and the remainder being is tin and silver.

Claim 5 (currently amended) A joint structure, ~~characterized in that~~ comprising bodies to be
joined are joined together by the tin-silver based lead-free solder of ~~any one of claims 1 to 4~~
claim 1.

Claim 6 (currently amended) The joint structure ~~according to~~ of claim 5, ~~characterized in that~~
wherein an electroless plating layer is provided on surfaces of said bodies to be joined.

Claim 7 (currently amended) The joint structure ~~according to~~ of claim 6, ~~characterized in that~~
wherein said _electroless _plating layer is a Ni-Pplating.